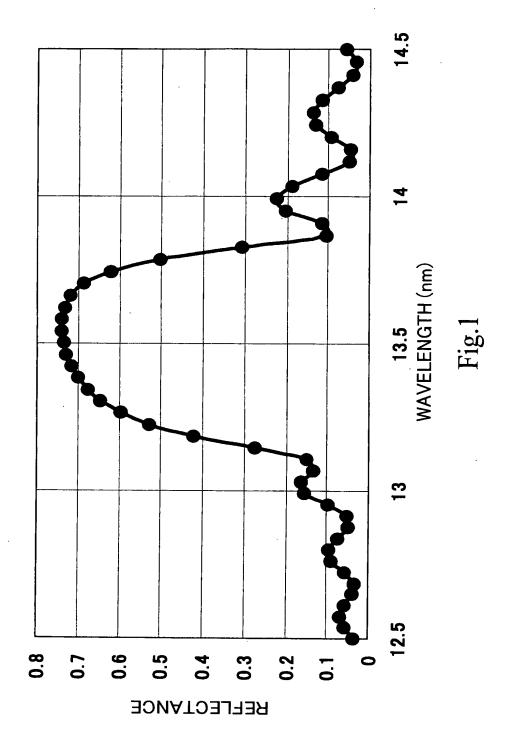
ï



2/22

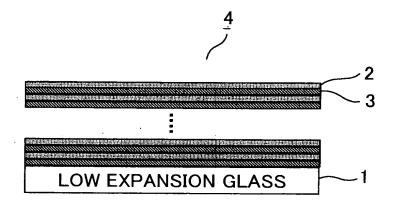


Fig.2

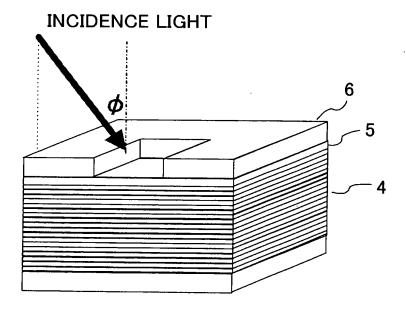
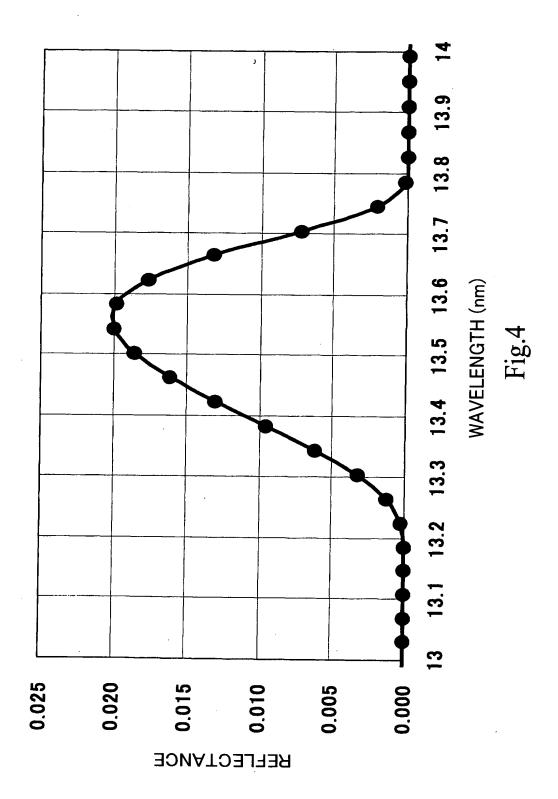
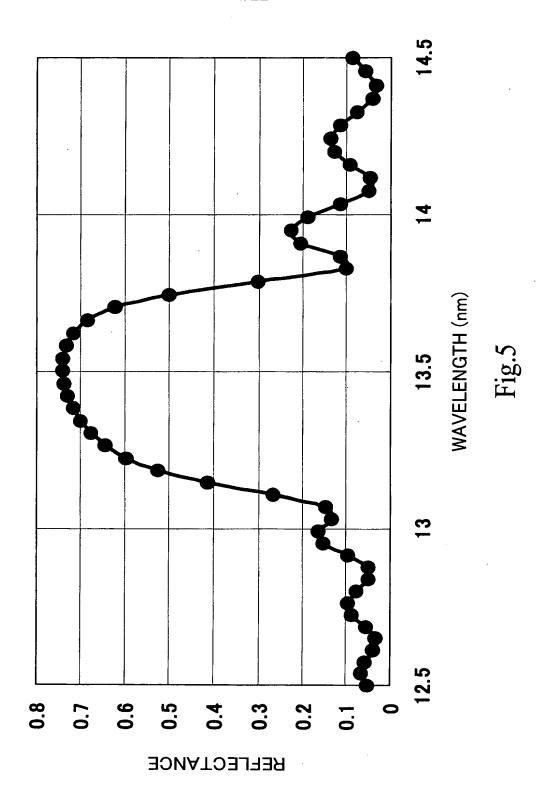
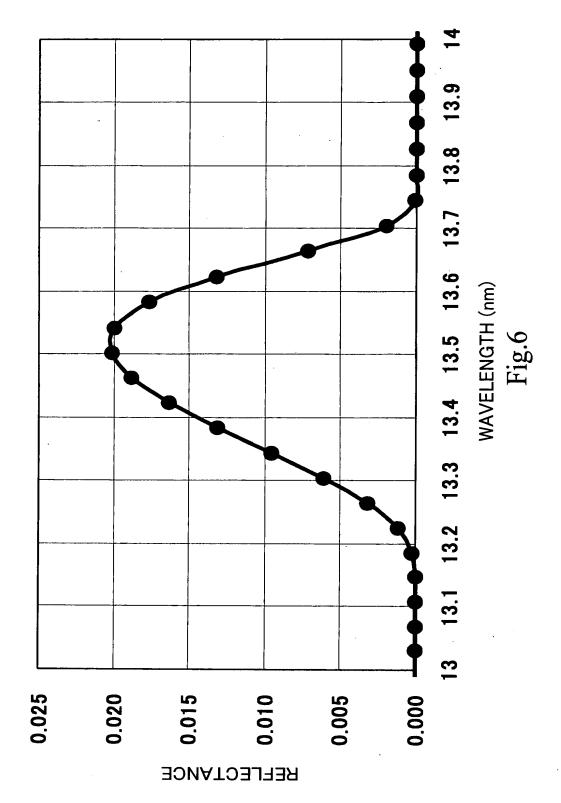


Fig.3







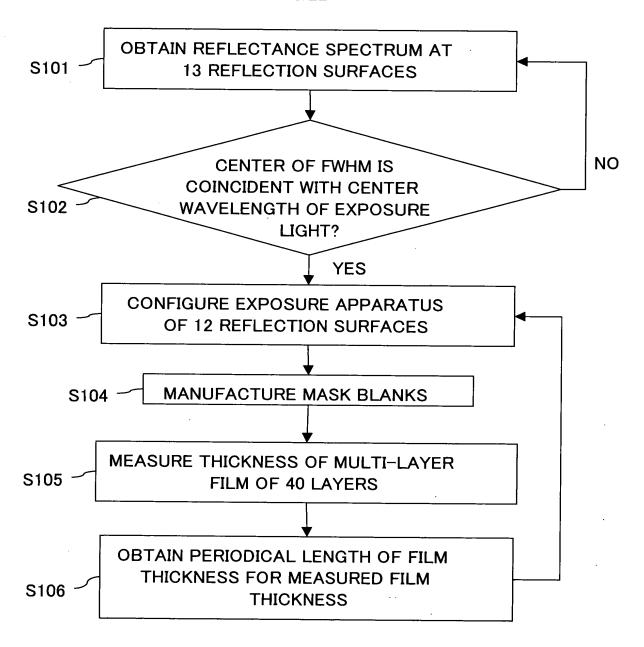


Fig.7

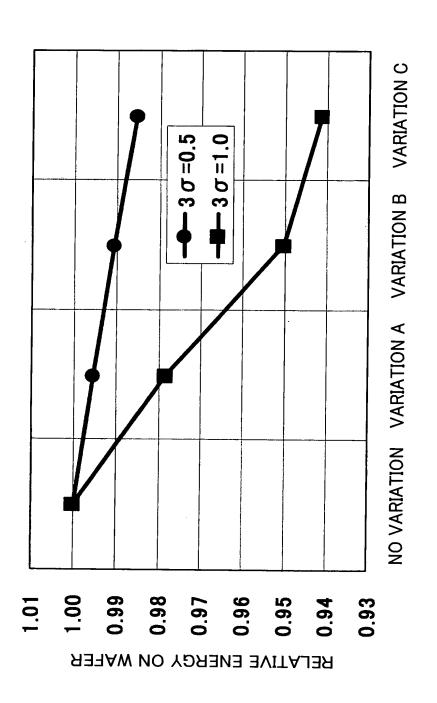
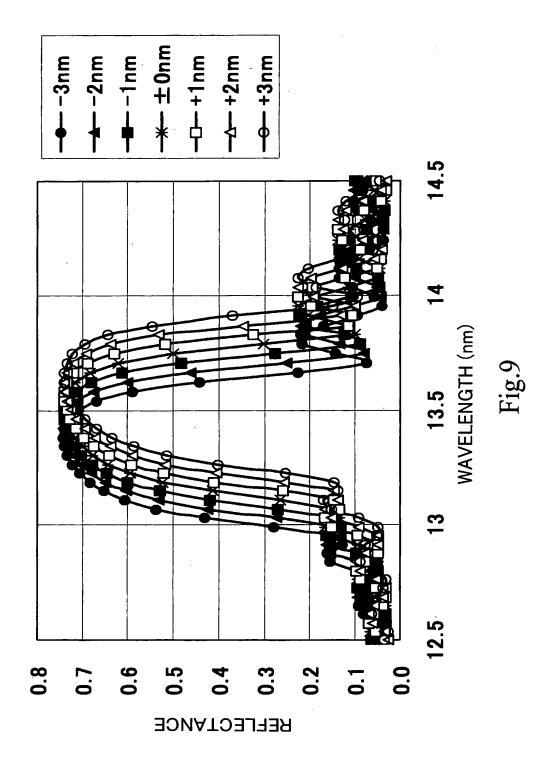
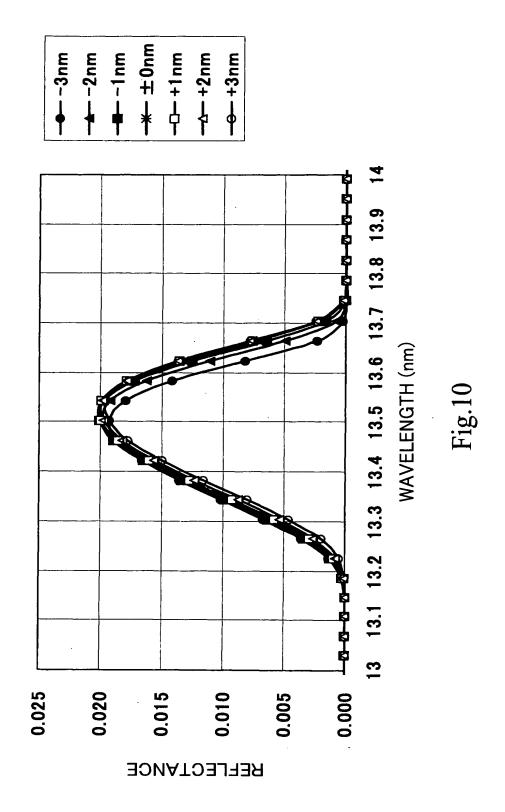
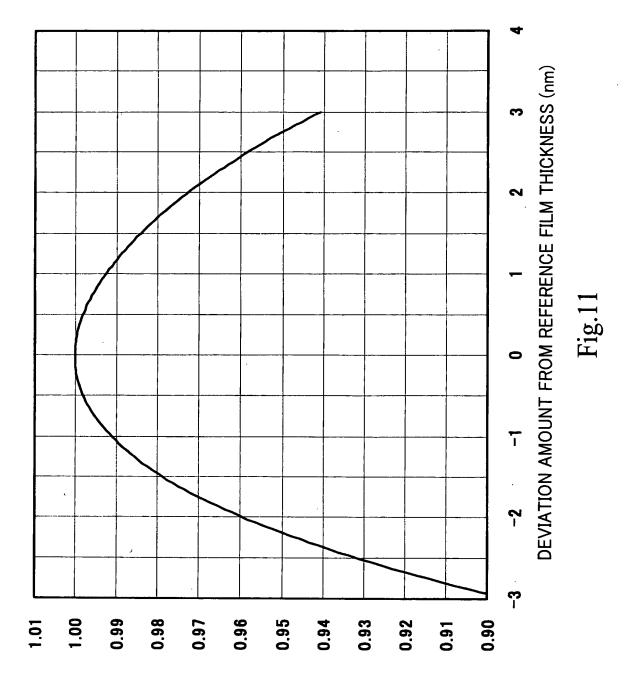


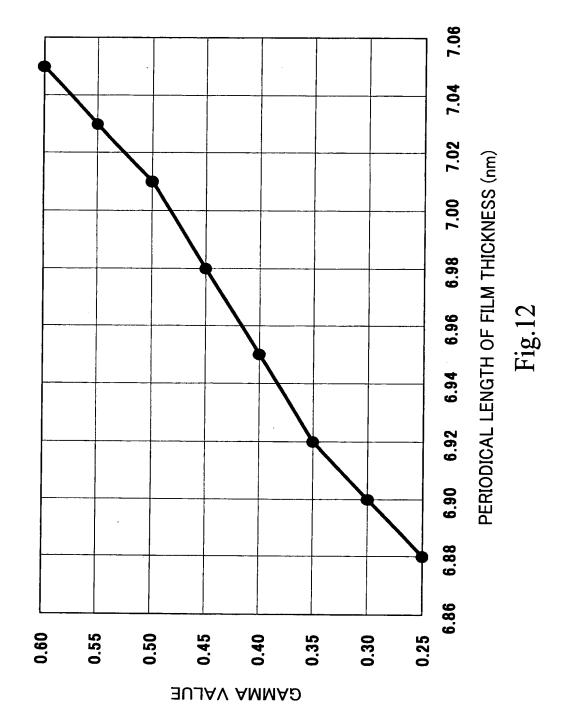
Fig.8

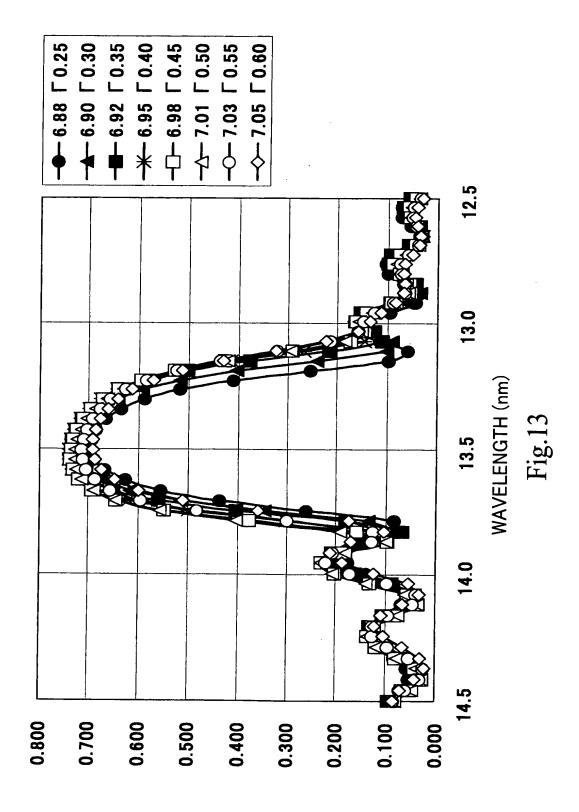


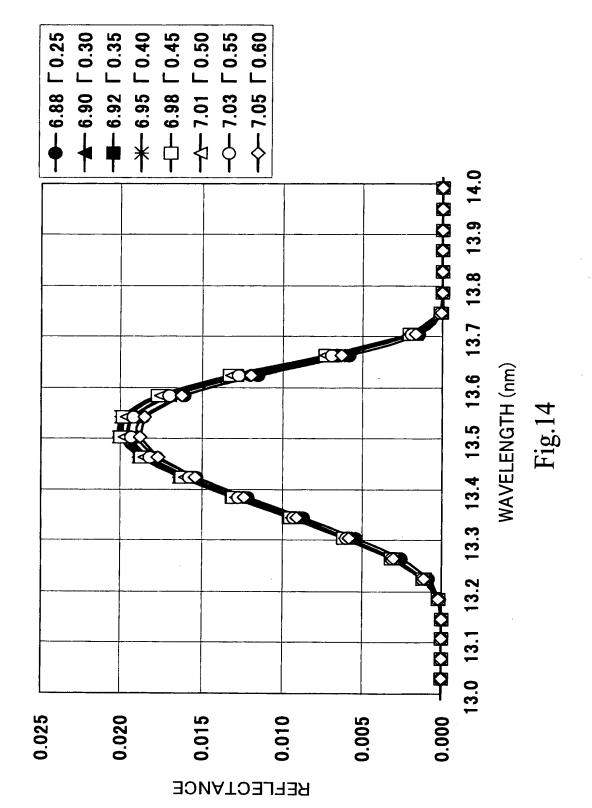


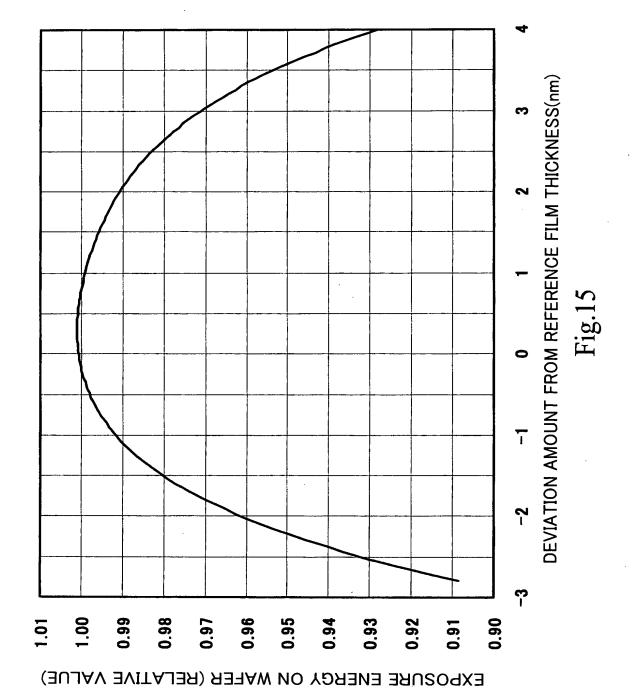


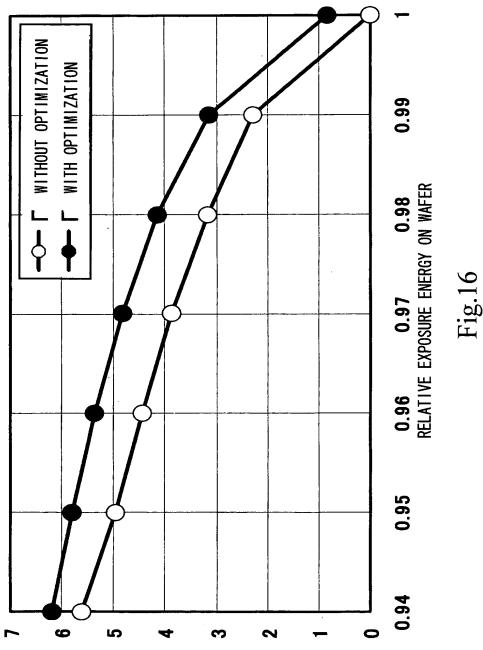
EXPOSURE ENERGY ON WAFER (RELATIVE VALUE)



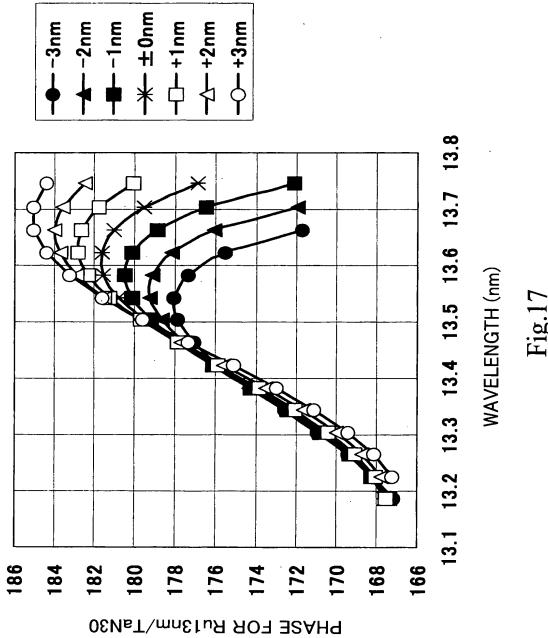


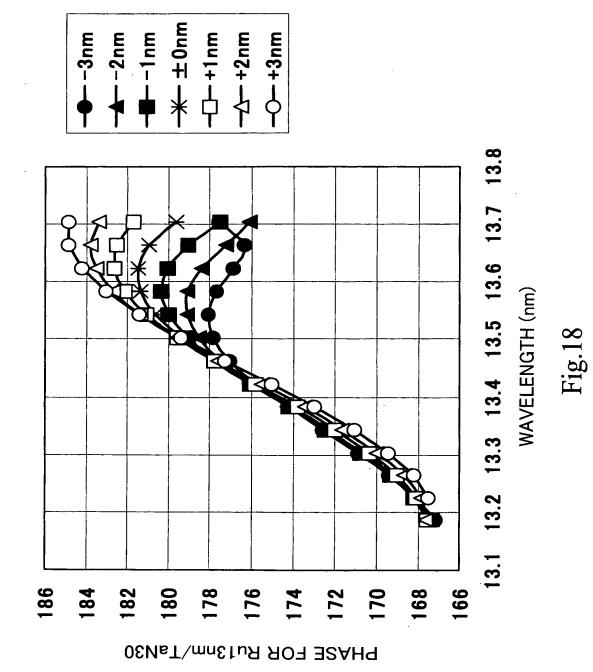


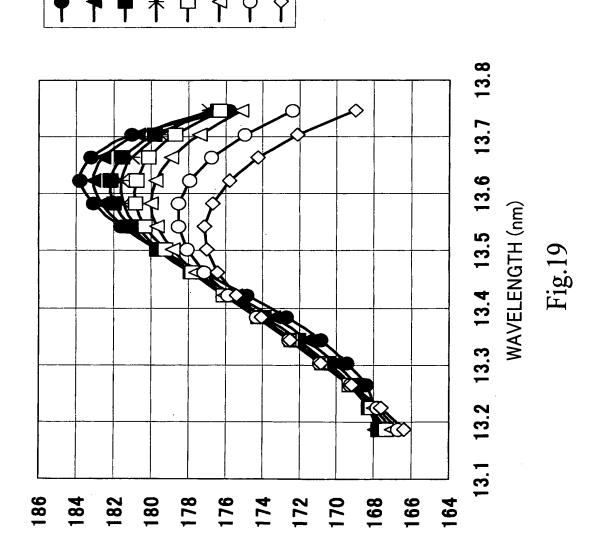




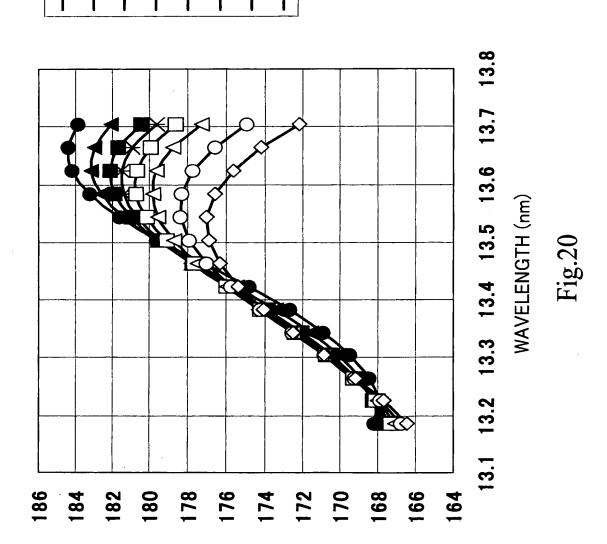
ALLOWABLE FILM THICKNESS VARIATION WIDTH (nm)





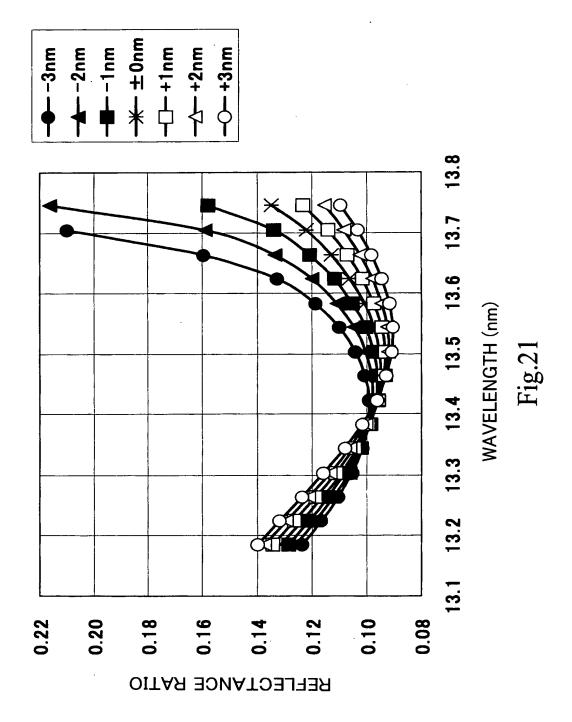


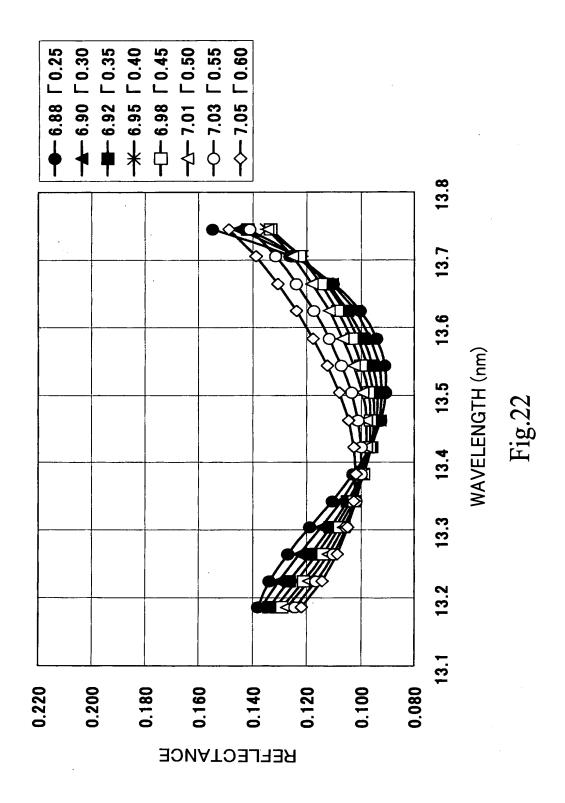
PHASE FOR Ru13nm/TaN30



PHASE FOR Ru13nm/TaN30

19/22





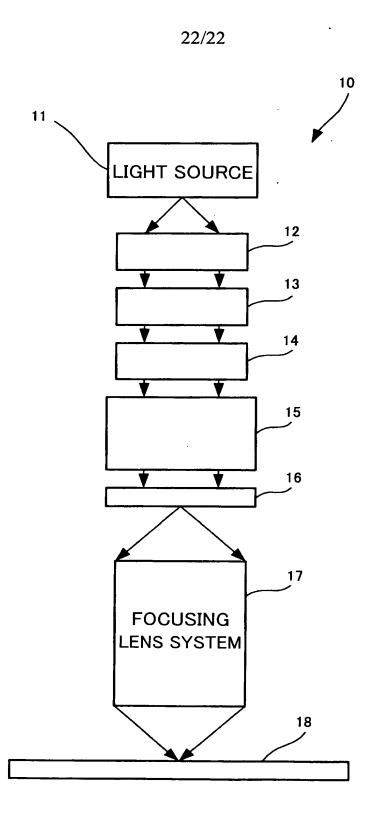


Fig.23